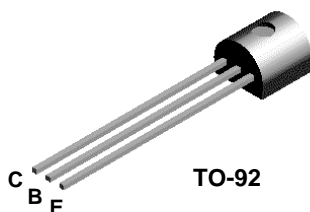
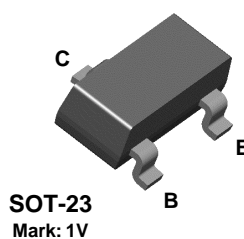


2N6427



MMBT6427



NPN Darlington Transistor

This device is designed for applications requiring extremely high current gain at collector currents to 1.0 A. Sourced from Process 05. See MPSA14 for characteristics.

Absolute Maximum Ratings*

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{CEO}	Collector-Emitter Voltage	40	V
V _{CB0}	Collector-Base Voltage	40	V
V _{EBO}	Emitter-Base Voltage	12	V
I _C	Collector Current - Continuous	1.2	A
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

TA = 25°C unless otherwise noted

Symbol	Characteristic	Max		Units
		2N6427	*MMBT6427	
P _D	Total Device Dissipation Derate above 25°C	625	350	mW
		5.0	2.8	mW/°CC
R _{θJA}	Thermal Resistance, Junction to Ambient	200	357	°C/W

*Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

NPN Darlington Transistor

(continued)

2N6427 / MMBT6427

Electrical Characteristics

TA = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
OFF CHARACTERISTICS					
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage*	$I_C = 10 \text{ mA}, I_B = 0$	40		V
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	$I_C = 100 \text{ }\mu\text{A}, I_E = 0$	40		V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	$I_E = 10 \text{ }\mu\text{A}, I_C = 0$	12		V
I_{CEO}	Collector Cutoff Current	$V_{CE} = 25 \text{ V}, I_B = 0$		1.0	μA
I_{CBO}	Collector Cutoff Current	$V_{CB} = 30 \text{ V}, I_E = 0$		50	nA
I_{EBO}	Emitter Cutoff Current	$V_{EB} = 10 \text{ V}, I_C = 0$		50	nA

ON CHARACTERISTICS

h_{FE}	DC Current Gain*	$I_C = 10 \text{ mA}, V_{CE} = 5.0 \text{ V}$ $I_C = 100 \text{ mA}, V_{CE} = 5.0 \text{ V}$ $I_C = 500 \text{ mA}, V_{CE} = 5.0 \text{ V}$	10,000 20,000 14,000	100,000 200,000 140,000	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 50 \text{ mA}, I_B = 0.5 \text{ mA}$ $I_C = 500 \text{ mA}, I_B = 0.5 \text{ mA}$		1.2 1.5	V V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C = 500 \text{ mA}, I_B = 0.5 \text{ mA}$		2.0	V
$V_{BE(on)}$	Base-Emitter On Voltage	$I_C = 50 \text{ mA}, V_{CE} = 5.0 \text{ V}$		1.75	V

SMALL SIGNAL CHARACTERISTICS

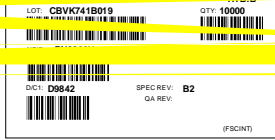
C_{obo}	Output Capacitance	$V_{CB} = 10 \text{ V}, I_E = 0,$ $f = 1.0 \text{ MHz}$		7.0	pF
C_{ibo}	Input Capacitance	$V_{BE} = 1.0 \text{ V}, I_C = 0,$ $f = 1.0 \text{ MHz}$		15	pF

*Pulse Test: Pulse Width $\leq 300 \text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$

TO-92 T



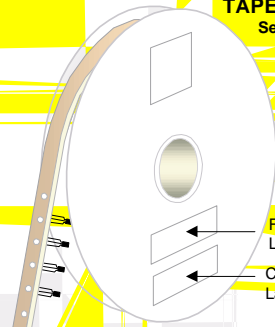
FSCINT Label sample



F63TNR Label sample



TAPE and REEL OPTION
 See Fig 2.0 for various Reeling Styles



5 Reels per Intermediate Box

F63TNR Label
 Customized Label

375mm x 267mm x 37mm

A

5 Reels per Intermediate Box

F63TNR

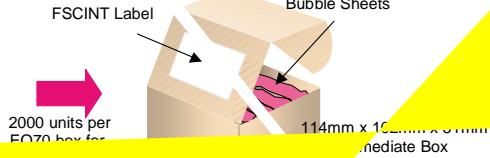
Intermediate Box

(TO-92)

EOL CODE
J18Z
J05Z
NO F

L34Z	94 (NON PROELECTRON SERIES), 96	NO LEADCLIP	2.0 K/BOX
	TO-92 STANDARD STRAIGHT FOR: PKG 94 (PROELECTRON SERIES BCXXX, BFXXX, BSRXXX), 97, 98		

BULK OPTION
 See Bulk Packing Information table



5 EO70 boxes per intermediate Box

Customized Label

10,000 units maximum per intermediate box for std option

TO-92 Tape and Reel Data, continued

TO-92 Reeling Style
Configuration: Figure 2.0

Machine Option "A" (H)

Style "A", D26Z, D70Z (s/h)

TO-92 Tape and Reel Data, continued

**TO-92 Tape and Reel Taping
Dimension Configuration: Figure 4.0**



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Ha	0.928 (+/- 0.025)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment (side/side)	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0.010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold - down Tape Width	WO	0.236 (+/- 0.012)
Hold - down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note : All dimensions are in inches.

**TO-92 Reel
Configuration: Figure 5.0**



ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

Note: All dimensions are in inches

TO-92 Package Dimensions



TO-92 (FS PKG Code 92, 94, 96)



Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.1977

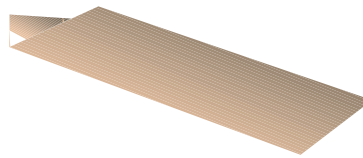
TO-92 (92,94,96)

PIN	92		94		96	
	B	F	B	F	B	F
1	E	D	E	D	B	S
2	B	S	C	G	E	D
3	C	G	B	S	C	G



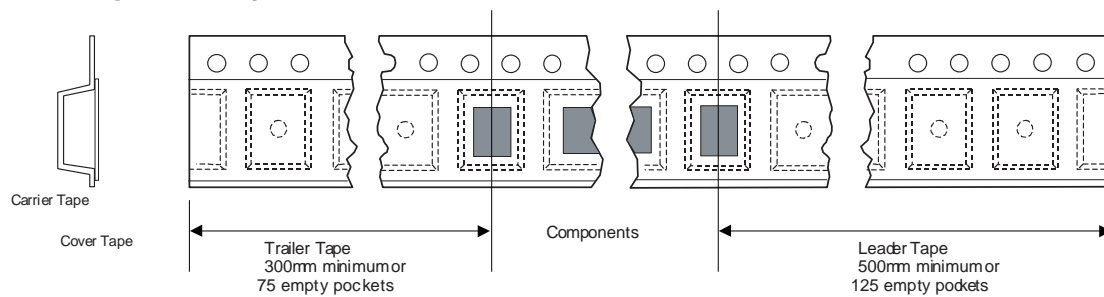
SOT-23 Packaging
Configuration: Figure 10

SOT-23 Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	187x107x183	343x343x64
Max qty per Box	24,000	30,000
Weight per unit (gm)	0.0082	0.0082
Weight per Reel (kg)	0.1175	0.4006
Note/Comments		



Human readable
Label

SOT-23 Tape Leader and Trailer
Configuration: Figure 20



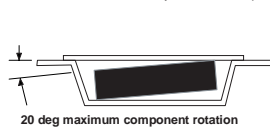
SOT-23 Tape and Reel Data, continued

SOT-23 Embossed Carrier Tape Configuration: Figure 3.0

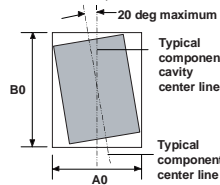


Dimensions are in millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SOT-23 (8mm)	3.15 ±0.10	2.77 ±0.10	8.0 ±0.3	1.55 ±0.05	1.125 ±0.125	1.75 ±0.10	6.25 min	3.50 ±0.05	4.0 ±0.1	4.0 ±0.1	1.30 ±0.10	0.228 ±0.013	5.2 ±0.3	0.06 ±0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

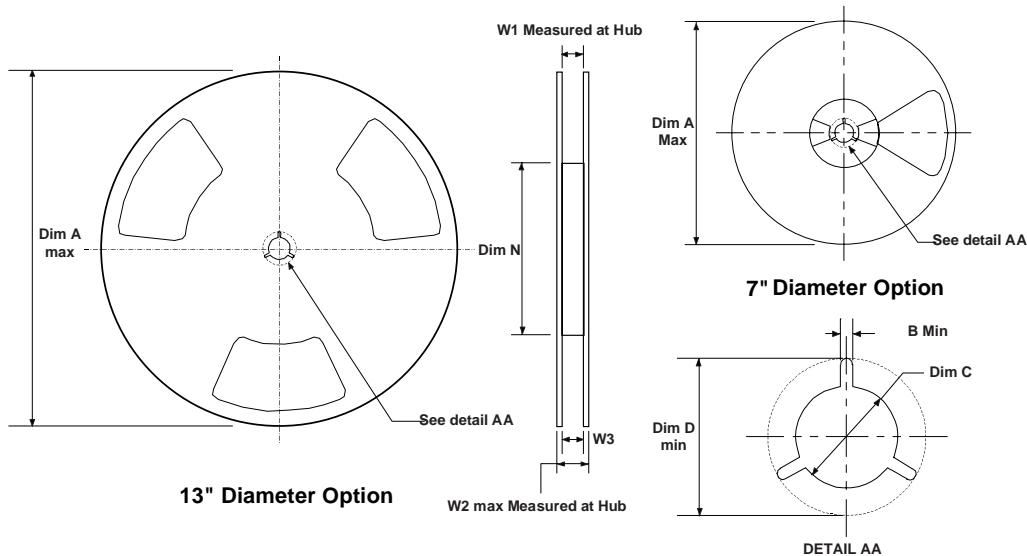


Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

SOT-23 Reel Configuration: Figure 4.0

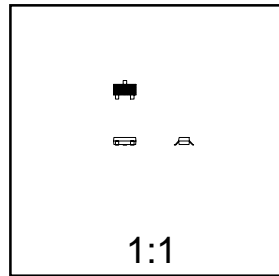


Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 -0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 -0.429 7.9 - 10.9

SOT-23 Package Dimensions



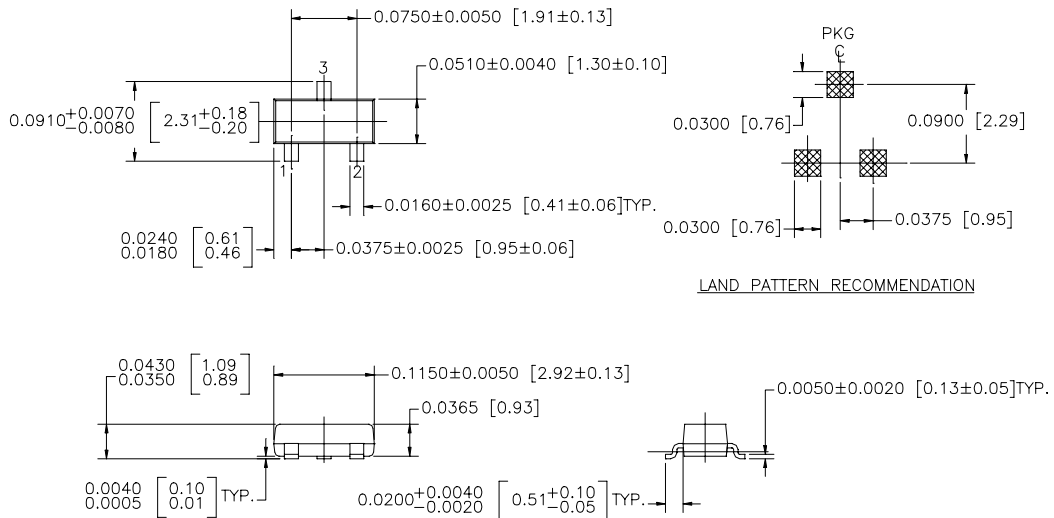
SOT-23 (FS PKG Code 49)



Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.0082



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTE : UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS
MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- REFERENCE JEDEC REGISTRATION TO-2

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E ² CMOS™	MICROWIRE™	SILENT SWITCHER®	
EnSigna™	OPTOLOGIC™	SMART START™	
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